

AMENDMENTS TO THE CLAIMS

1. (currently amended) A method of fabricating a precision circuit element comprising:

creating one or more redundant circuit elements within an integrated circuit substrate by damascene processing;

creating one or more trim circuit elements within said integrated circuit substrate by damascene processing;

creating one or more links coupling said redundant circuit elements to said trim circuit elements, said one or more links having a first end and a second end, said first end connected to one of said trim circuit elements and said second end connected to another of said trim circuit elements such that no trim circuit element is connected to more than two of said links;

selectively activating one or more of said links to achieve a desired capacitance.

2. (original) The method of claim 1 where said links are fusible links and said activating comprises blowing of said fusible links.

3. (original) The method of claim 1 where said links are antifuses and said activating comprises fusing of said antifuses.

4. (currently amended) A method of fabricating a precision capacitor comprising:

creating one or more redundant plates within an integrated circuit substrate by damascene processing;

creating one or more trim plates within said integrated circuit substrate by damascene processing;

creating one or more links coupling said redundant plates to said trim

plates, said one or more links having a first end and a second end, each of said first ends connected to one of said redundant plates and each of said second end connected to one of said trim plates;

creating a common plate capacitively coupled to said redundant plates and said trim plates; and

selectively activating one or more of said links to achieve a desired capacitance.

5. (original) The method of claim 4 where said links are fusible links and said activating comprises blowing of said fusible links.

6. (original) The method of claim 4 where said links are antifuses and said activating comprises fusing of said antifuses.

7. (withdrawn) A method of fabricating a precision capacitor comprising:
creating a capacitor having a first plate and a second plate, said first plate capacitively coupled to said second plate;
creating a plurality of trim capacitors each having a first trim plate and a second trim plate said first trim plate capacitively coupled to said second trim plate;
connecting, in series, said capacitor and said trim capacitors;
connecting one or more links in parallel with each of said trim capacitors;
and
selectively activating said one or more of said links to achieve a desired capacitance.

8. (withdrawn) The method of claim 7 where said links are fusible links and said activating comprises blowing of said fusible links.

9. (withdrawn) The method of claim 7 where said links are antifuses and said

activating comprises fusing of said antifuses.

10. (withdrawn) A method of forming a capacitor comprising:
- depositing a first insulator film;
 - etching a first trough;
 - depositing a first liner within said first trough;
 - depositing a first conductive electrode within said trough;
 - polishing off excess material;
 - depositing a second insulator film over said first conductive electrode;
 - etching a second trough extending through said second insulator film extending to said first copper electrode;
 - cleaning surfaces;
 - applying a thin dielectric over said exposed first copper electrode;
 - depositing a second liner;
 - depositing a second copper electrode; and
 - polishing off excess material.
11. (withdrawn) The method of claim 10 wherein said applying is depositing a thin dielectric.
12. (withdrawn) The method of claim 10 wherein said applying is growing a thin dielectric.